

INSERTION OF ELECTRICAL COMPONENT WITHIN A VIA OF A PRINTED CIRCUIT BOARD

A printed circuit board and method for reducing the impedance within the
5 reference path and/or saving space within the printed circuit board. In one embodiment
of the present invention, a printed circuit board comprises a plurality of conductive
layers. The printed circuit board further comprises two or more vias for interconnecting
two or more conductive layers. The printed circuit board further comprises an electrical
10 component embedded in a particular via between two conductive layers to reduce the
impedance within the reference path and/or save space within the printed circuit board.

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